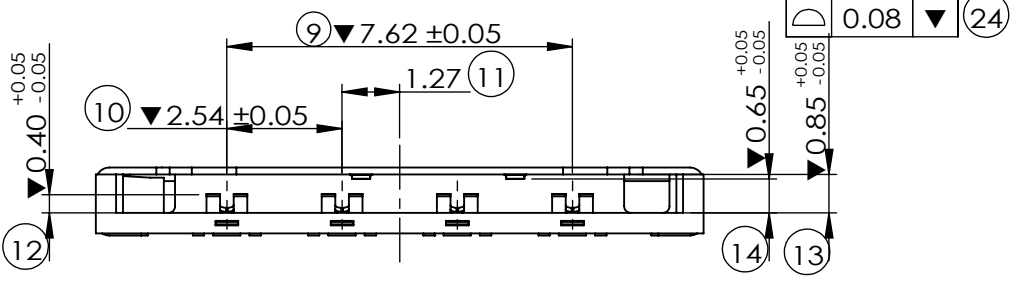
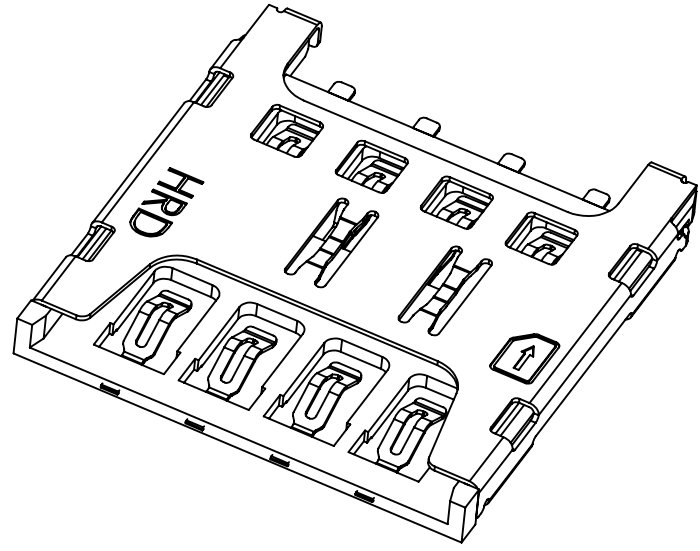
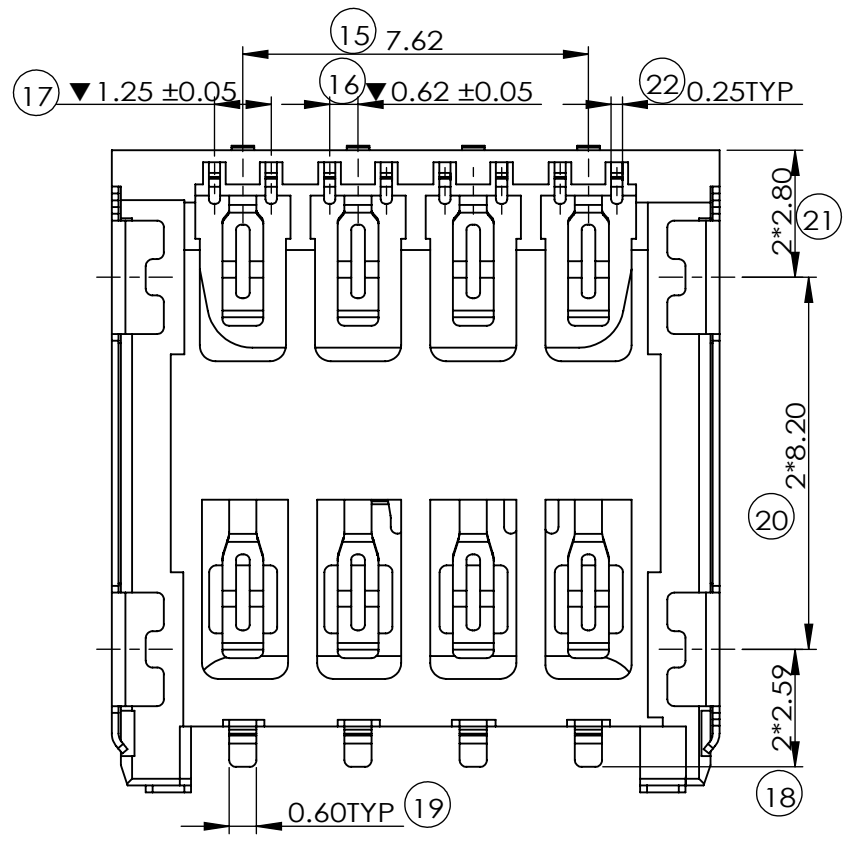


- NOTES:
- MATERIAL:
HOUSING: LCP, BLACK, UL 94V-0
CONTACT: PHOSPHOR BRONZE, T=0.10MM
SHELL: STAINLESS STEEL T=0.15MM
 - FINISH:
CONTACT: 50U' MIN PLATING OVER ALL
GOLD FLASH ON THE CONTACT AREA AND SOLDER AREA
SHELL: SELECTIVE GOLD FLASH IN SOLDER TAIL AREA
30U' NI MIN. PLATING OVER ALL
 - ALL DIMENSIONS MARKED ▼ MUST BE CONTROLLED BY QC
 - ALL DIMENSIONS MARKER (XX) MUST BE MEASURED BY FAI.
 - RATED PARAMETERS OF CONNECTOR
5-1. Operating temperature: -40°C to 70°C
5-2. Rated Current: 0.5A
5-3. Rated Voltage: 30V DC Per Contact
 - ELECTRICAL MECHANICAL ENVIRONMENTAL
6-1. Dielectric withstanding Voltage: 500V AC 1min.
6-2. Insulation Resistance: 1000 MΩMin.
6-3. Normal Force: 30g Min. Per Pin
6-4. Durability: 3000 cycles
6-5. Contact Resistance: 50mΩ MAX.




P.C.B LAYOUT (TOLERANCE:±0.05)

SIM CARD PIN NO.	PIN NO.
P1	VCC
P2	RST
P3	CLK
P4	RESERVED
P5	GND
P6	VPP
P7	I/O
P8	RESERVED



NO.	DESCRIPTION	PART NO.	MATERIAL	REMARK
1	CONTACT	S34-TF015001	C5210-SH	
2	HOUSING	S34-MB015001	LCP-S475	
3	SHELL	S42-SF015000	SUS304-H	

UNITS: mm	GENERAL TOLERANCE		DRAW:	PART NO: S34-2B08F15A
DATE: 09/09/2015	X. ±0.15 .X ±0.10	X.° ±2.00 .X° ±1.00	CHECKED:	TITLE: MICRO SIM CARD 成品H=1.50mm
SCALE: 8 / 1	.XX ±0.05 .XXX ±0.05	.XX° ±0.50	APPROVE:	DRAWING NO:
SHEET: 1 / 1	MATERIAL:		 鸿日达科技股份有限公司 HONGRIDA ELECTRONIC TECHNOLOGY CO.,LTD.	
REV. A	FINISH: SEE NOTE			

REV.	ECN NO.	DESCRIPTION	DATE